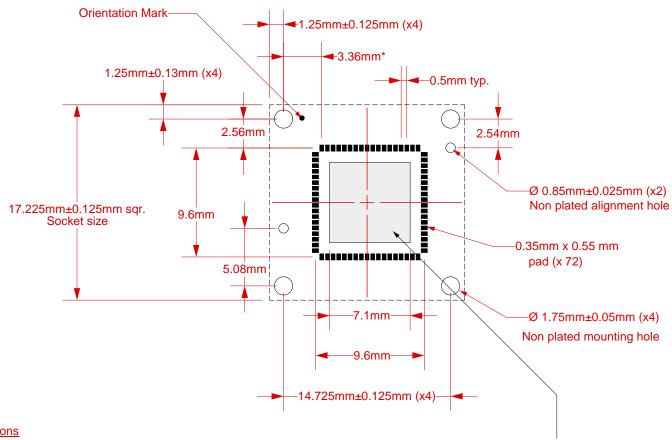


SG-MLF-7025 Drawing	Status: Released	Scale	: -	Rev:B
© 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: J. Glab		Date: 6/26/07	
	File: SG-MLF-7025 Dwg.mcd		Modified: 11/11/14, DH	

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

*Note: MLF pattern is not symmetrical with respect to the mounting holes. It is offset 0.25mm to the right of center.



Target PCB Recommendations

Total thickness: 1.6mm min. Plating: Gold or Solder finish

PCB Pad height: Same or higher than solder mask

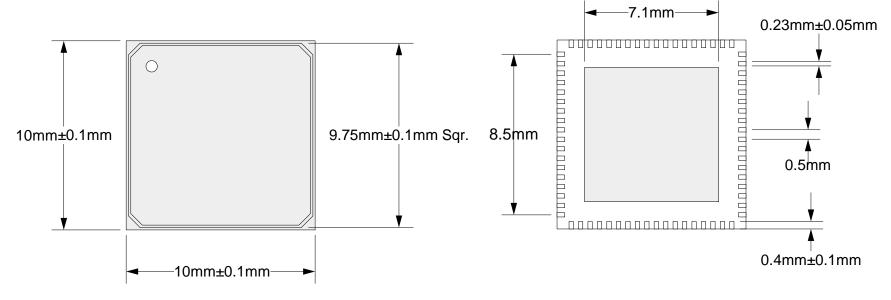
NOTE: Steel backing plate may be required based on end user's application

**** To effectively conduct heat away from the package a thermal pad is recommended with vias spaced 1.0 to 1.2 mm pitch and a diameter of 0.3 to 0.33 mm. Ideally 1 via for every 3 leads has been shown to work well.

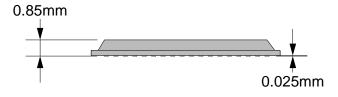
SG-MLF-7025 Drawing	Status: Released	Scale: -		Rev:B
© 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: J. Glab		Date: 6/26/07	
	File: SG-MLF-7025 Dwg.mcd		Modified: 11/11/14, DH	

PAGE 2 of 3

Compatible MLF package



Top View Bottom View



Side View

Recommended PCB Layout Tolerances: ± 0.025 mm unless stated otherwise. All dimensions are in mm.

SG-MLF-7025 Drawing	Status: Released	Scale: -		Rev: B
© 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: J. Glab		Date: 6/26/07	
	File: SG-MLF-7025 Dwg.mcd		Modified: 11/11/14, DH	

PAGE 3 of 3